FNK Semiconductor

## FNK N-Channel Enhancement Mode Power MOSFET

Description

The FNK08N03D uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- V_{DS} =30V, I_D =80A
  $R_{DS(ON)}$ <5.9mΩ @ V_{GS}=10V (Typ:5mΩ)

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
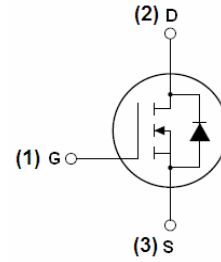
Schematic diagram
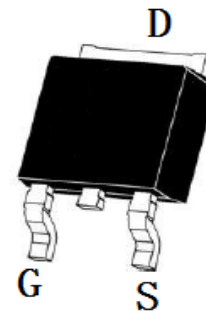
TO-252-2L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
FNK08N03D	FNK08N03D	TO-252	-	-	-

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	80	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	57	A
Pulsed Drain Current	I_{DM}	320	A
Maximum Power Dissipation	P_D	110	W
Single pulse avalanche energy [Note 5]	E_{AS}	108	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case[Note 2]	$R_{\theta JC}$	1.36	℃/W

Electrical Characteristics (T$_A$=25℃ unless otherwise noted)

| Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250µA	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V,V_{GS}=0V	-	-	1	µA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics [Note 3]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250µA	0.7	1.2	1.7	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=20A	-	5.0	5.9	mΩ
Forward Transconductance	g_{FS}	V_{DS}=10V,I_D=20A	50	-	-	S
Dynamic Characteristics [Note4]						
Input Capacitance	C_{Iss}	V_{DS}=25V,V_{GS}=0V, F=1.0MHz		2155		PF
Output Capacitance	C_{oss}			275		PF
Reverse Transfer Capacitance	C_{rss}			220		PF
Switching Characteristics [Note 4]						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=15V,I_D=30A V_{GS}=4.5V,R_{GEN}=1.8Ω	-	11	-	nS
Turn-on Rise Time	t_r		-	160	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	25	-	nS
Turn-Off Fall Time	t_f		-	60	-	nS
Total Gate Charge	Q_g	V_{DS}=15V,I_D=30A, V_{GS}=10V		70		nC
Gate-Source Charge	Q_{gs}			8.8		nC
Gate-Drain Charge	Q_{gd}			16.3		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage [Note 3]	V_{SD}	V_{GS}=0V,I_S=30A	-	-	1.2	V
Diode Forward Current [Note 2]	I_S	-	-	-	100	A
Reverse Recovery Time	t_{rr}	TJ = 25°C, IF = 30A di/dt = 100A/µs[Note3]	-	56	-	nS
Reverse Recovery Charge	Qrr		-	110	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, t ≤ 10 sec.

3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

4. Guaranteed by design, not subject to production

5. EAS condition：Tj=25℃,V_{DD}=15V,V_G=10V,L=0.5mH,Rg=25Ω
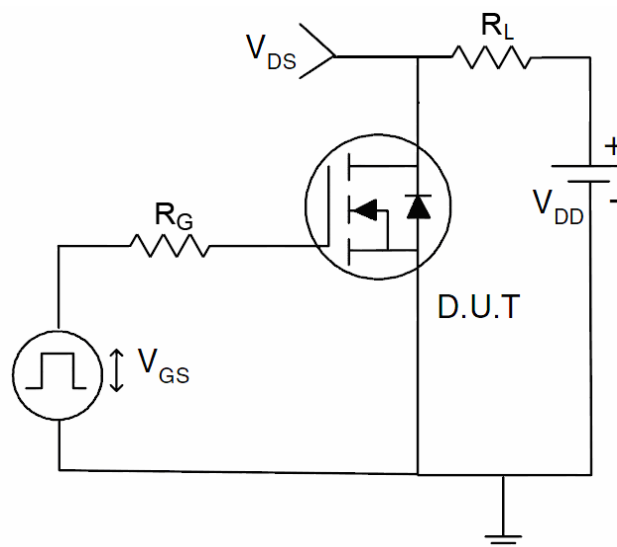
Test circuit

1）E$_{AS}$ test Circuits
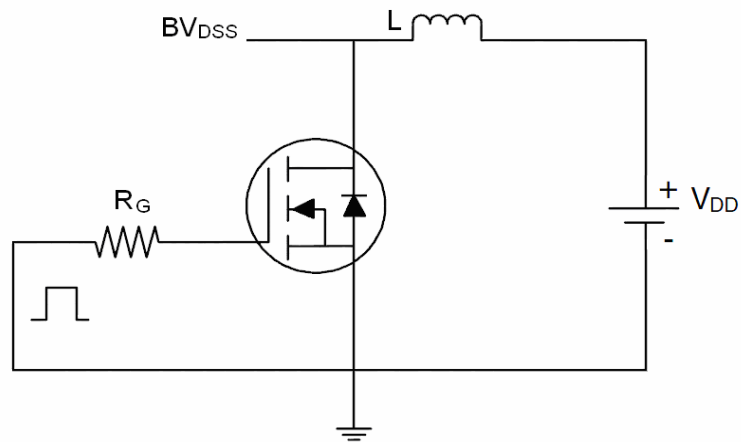
2）Gate charge test Circuit:
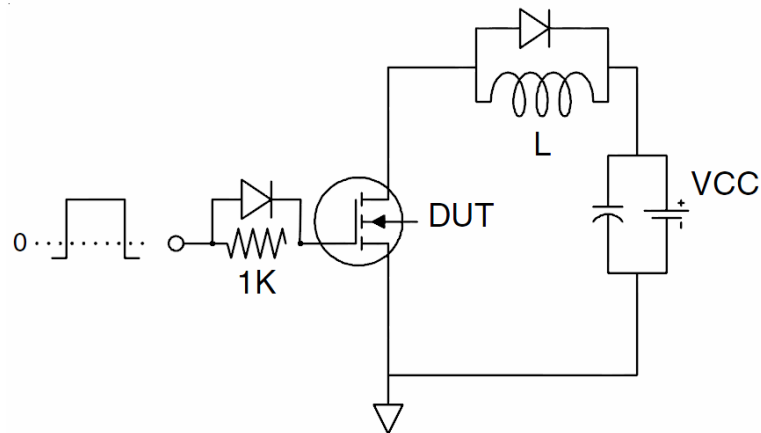
3）Switch Time Test Circuit：

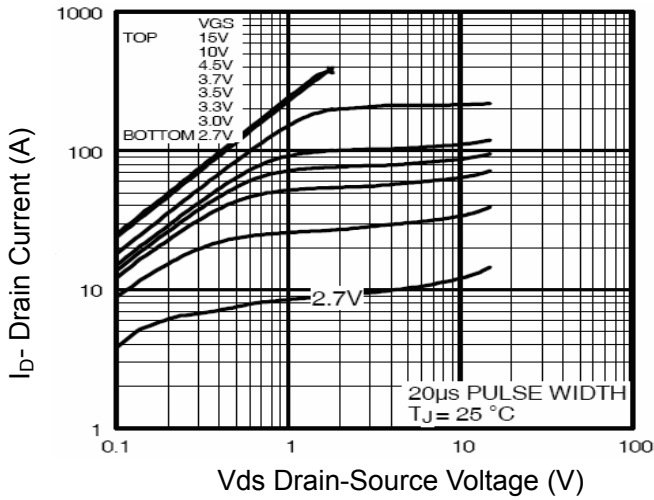## Typical Electrical and Thermal Characteristics (Curves)
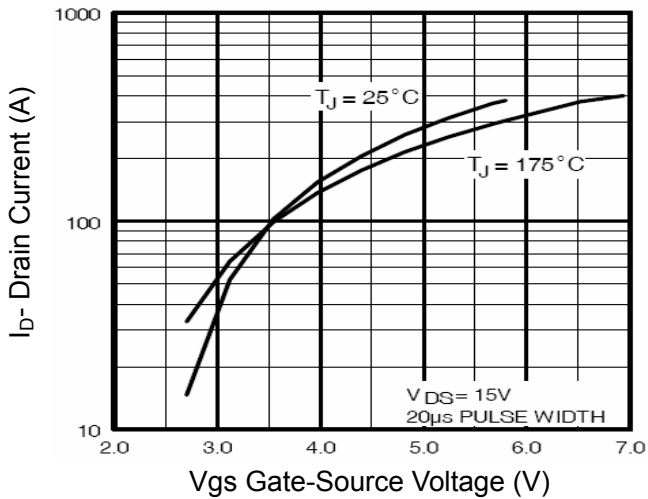
Figure 1 Output Characteristics
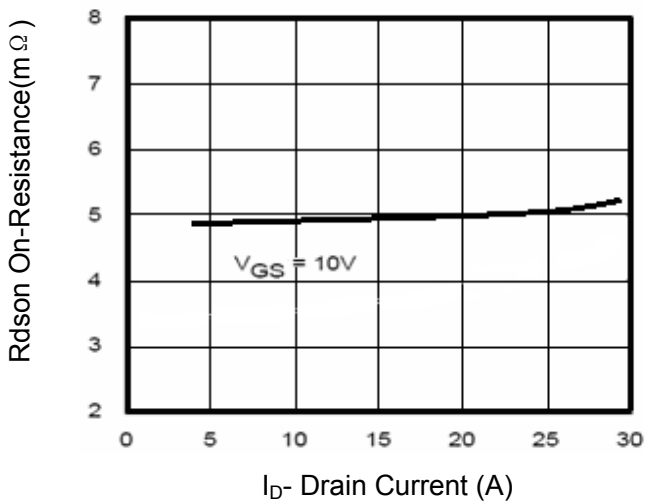
Figure 2 Transfer Characteristics

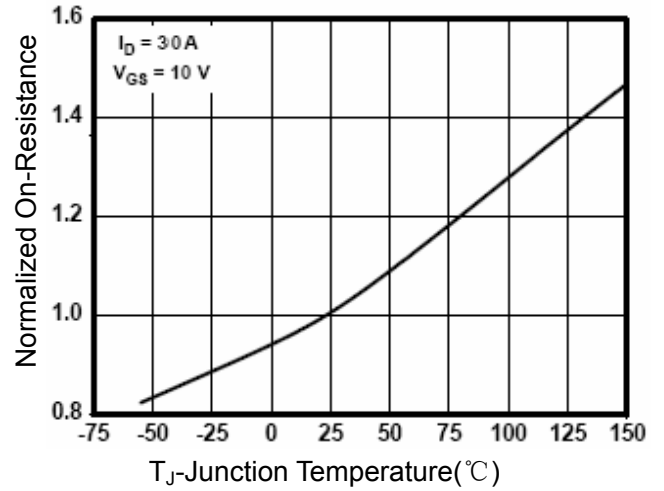**Figure 3 Rdson- Drain Current**

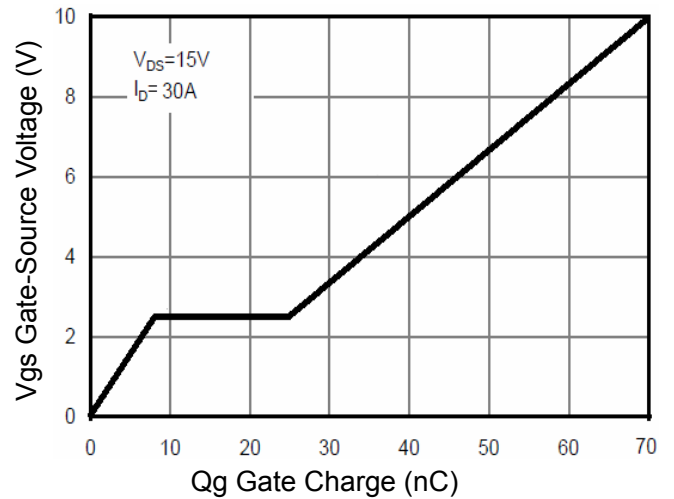**Figure 4 Rdson-JunctionTemperature**
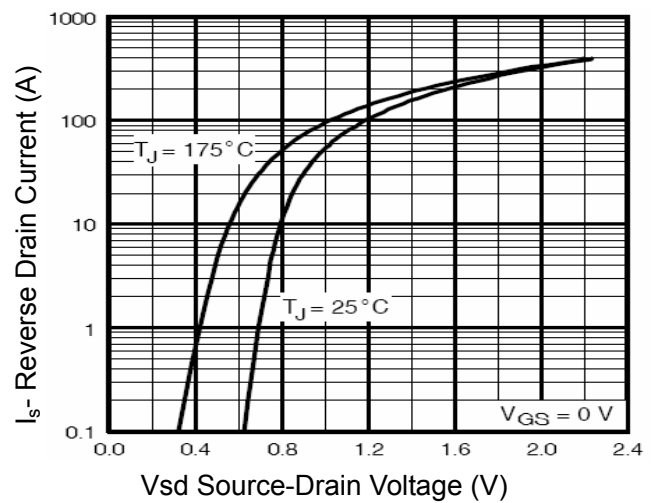
Figure 5 Gate Charge
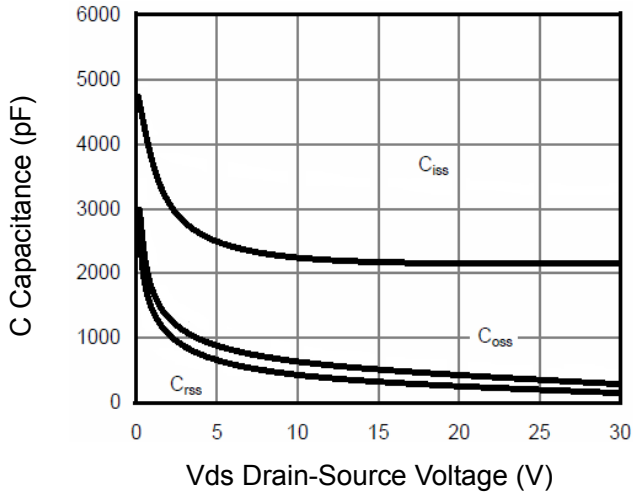
Figure 6 Source- Drain Diode Forward
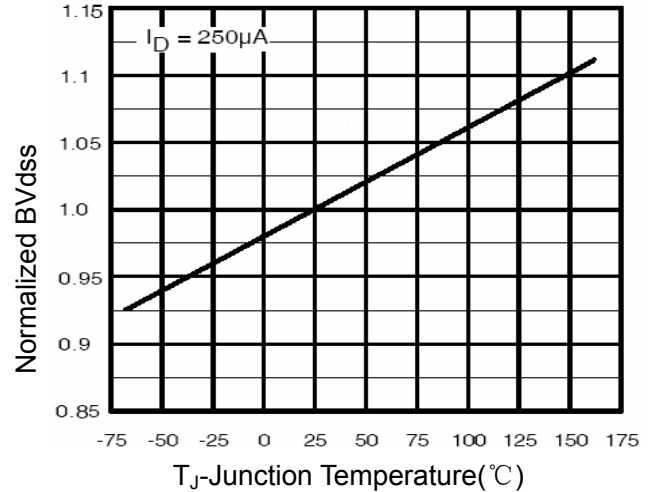
Figure 7 Capacitance vs Vds
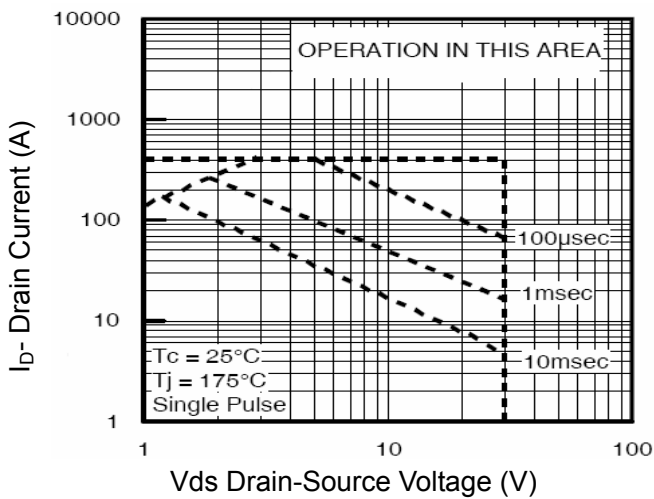
Figure 9 BV$_{DSS}$ vs Junction Temperature

Figure 8 Safe Operation Area
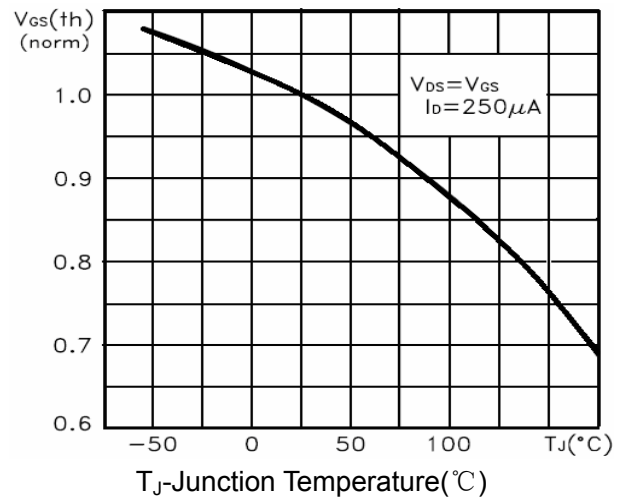
Figure 10 V$_{GS(th)}$ vs Junction Temperature

Notes:
1. Duty factor D = t_1 / t_2
2. Peak T$_J$ = P$_{DM}$ x Z$_{thJC}$ + T$_C$
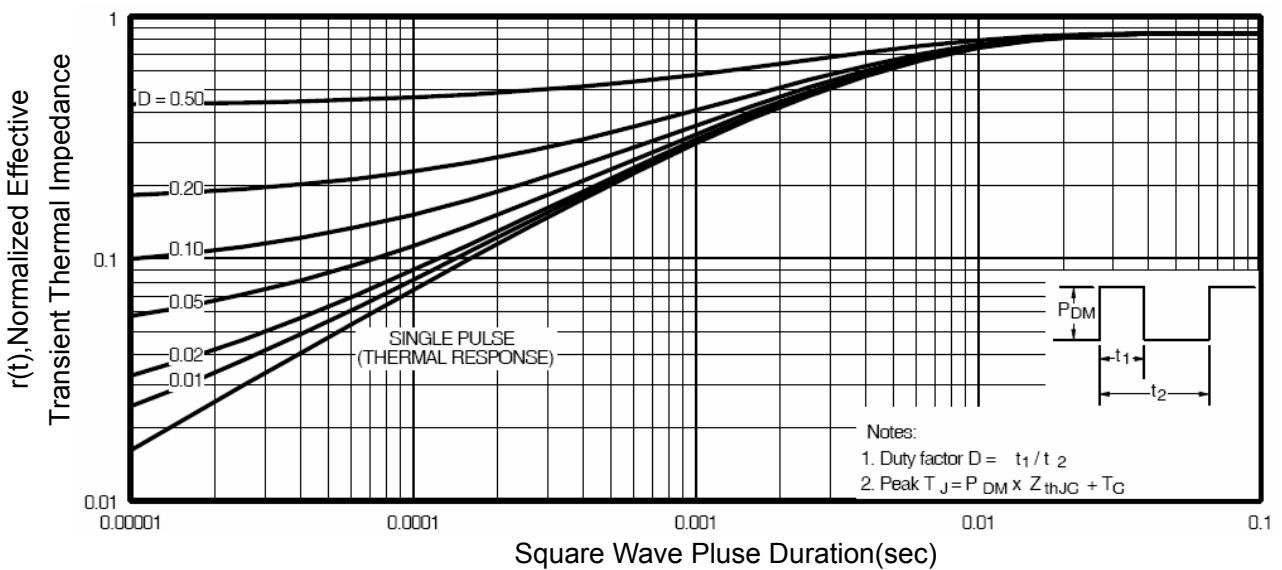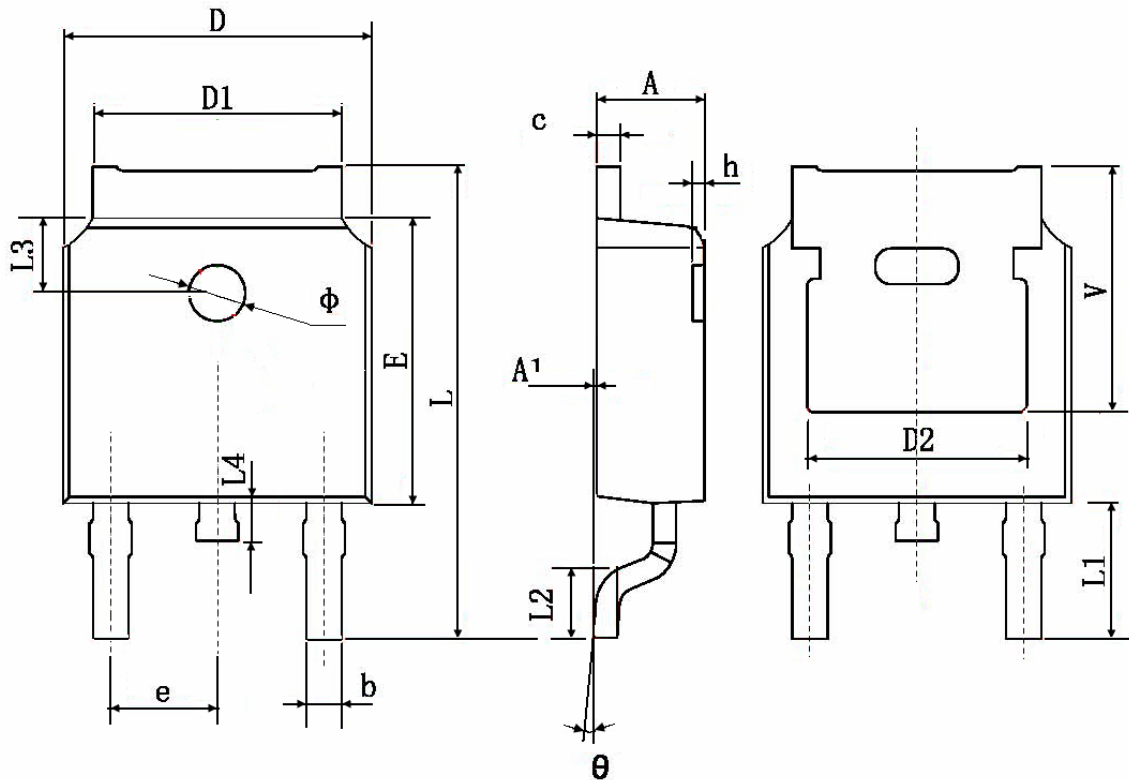
Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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